



Linking your dreams
LINTEC Corporation

**Creating the Future
with Adhesive Technologies**

Linkage + Technology
LINTEC

Company information

- Head Office:
Itabashi-ku, Tokyo, Japan
- Securities Code:
7966 (Tokyo Stock Exchange, Prime Market)
- Established: October 15, 1934
- Common Stock: 23.3 billion yen (as of March 31, 2023)
- Number of Employees: 5,418 (as of March 31, 2023)
- Net Sales: 284.6 billion yen (year ended March 31, 2023)
- Business Activities: Development, manufacture, and marketing of adhesive products and related equipment, specialty paper, release paper and film, etc.
- Consolidated Subsidiary: 3 companies (Japan)
38 companies (Overseas)



Company history

1934: Establishment of FUJI SHIKO CORPORATION,
manufacturer of gummed tape (Itabashi, Tokyo)

1960: Started production and sales of adhesive paper and film
for labels

Subsequently expanded adhesive operations in industrial
fields such as motorcycle, automobile, decorative materials
for exteriors and others

1984: The name was changed to FSK CORPORATION in 1984

1986: Developed UV curable dicing tape and made full-scale
entry into the semiconductor-related product field

1987: Acquired MADICO, INC. (USA)

1990: Merged with SHIKOKU PAPER CO., LTD., and
SOHKEN KAKO CO., LTD.

Name was changed to LINTEC Corporation

Expanded business activities, from specialty paper, release
paper and film to the fields of adhesive paper and film,
and related equipment

1991: Made full-scale entry into optical display-related product field



Company history

1994: PT. LINTEC INDONESIA was established

2000: LINTEC INDUSTRIES (MALAYSIA) SDN. BHD.
was established

2002: LINTEC (SUZHOU) TECH CORPORATION
was established

LINTEC SPECIALITY FILMS (KOREA), INC., was established

2003: LINTEC SPECIALITY FILMS (TAIWAN), INC., was established

2004: LINTEC KOREA, INC., was established

2011: LINTEC (THAILAND) CO., LTD., was established

2016: Acquired MACTAC AMERICAS, LLC

2021: Acquired DURAMARK PRODUCTS, INC. (USA)

2022: Acquired SPINNAKER PRESSURE SENSITIVE PRODUCTS LLC (USA)

2023: Acquired LABEL SUPPLY (CANADA)



LINTEC (SUZHOU) TECH CORPORATION



MACTAC AMERICAS, LLC

Performance trends / Net sales, Operating income

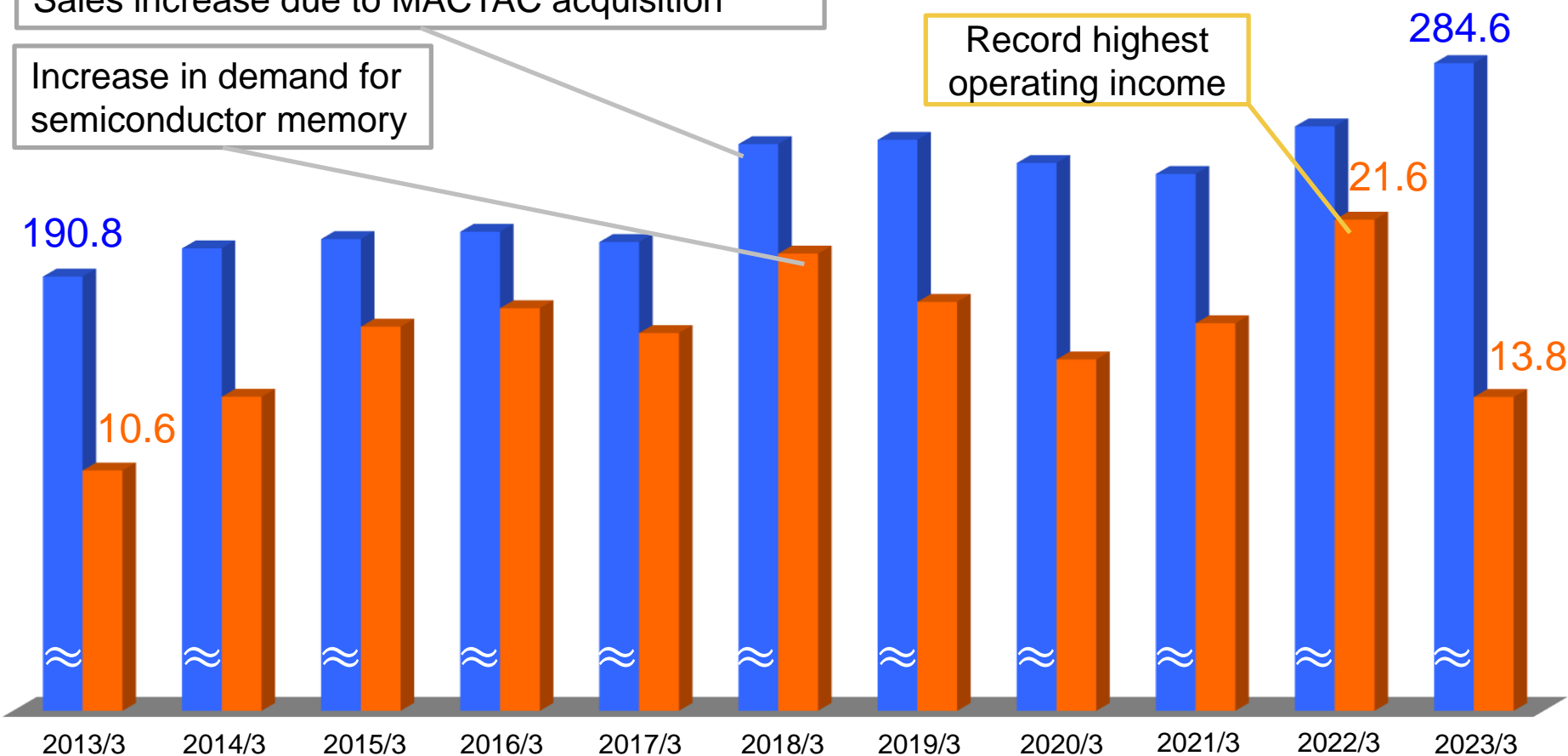
Unit: Billion yen ■ Net sales ■ Operating income

Sales increase due to MACTAC acquisition

Increase in demand for semiconductor memory

Record highest operating income

Record highest net sales



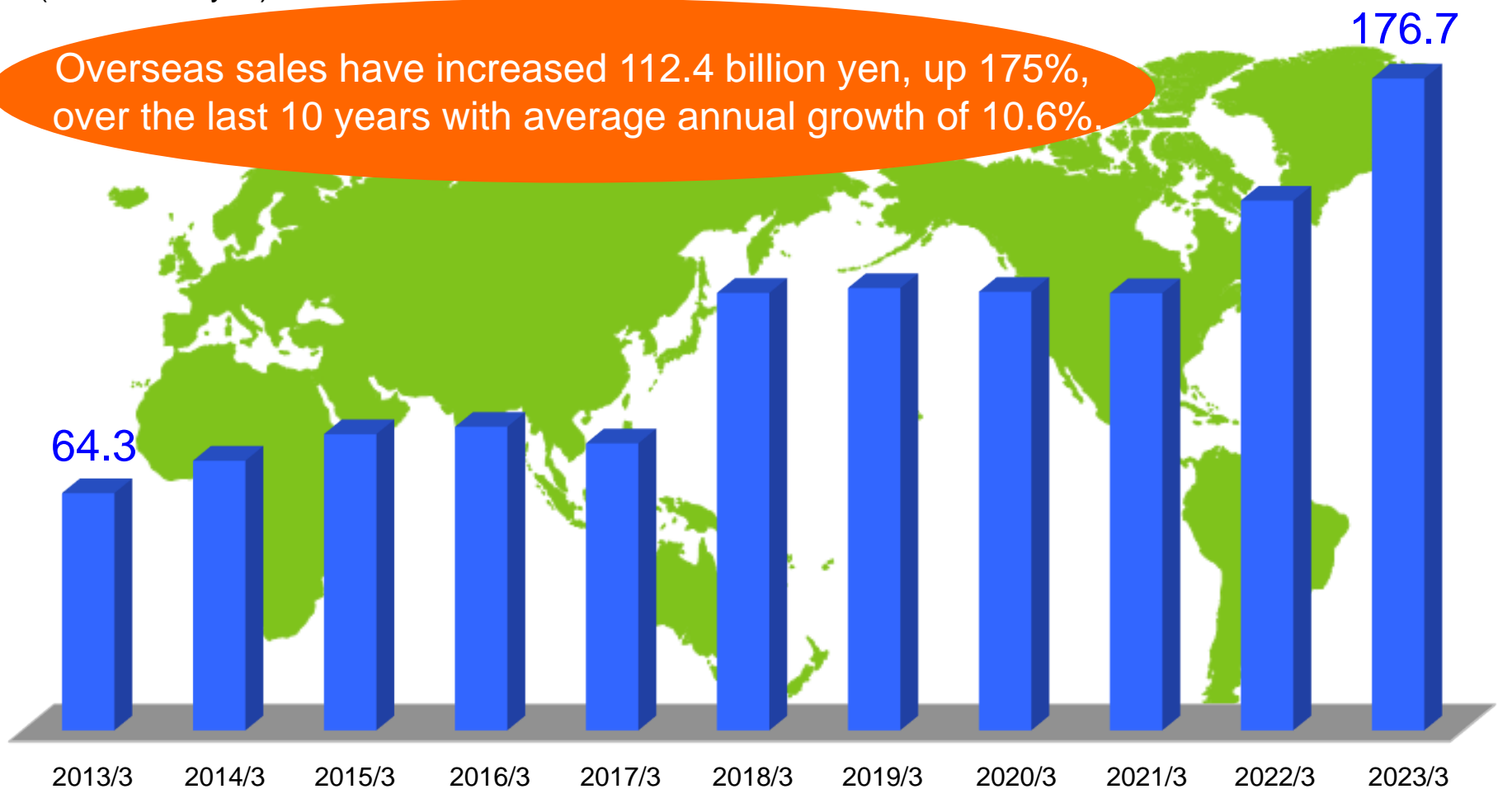
The impact of financial crisis in Europe and the Great East Japan Earthquake, etc.

Trade friction between the U.S. and China and the spread of COVID-19, etc.

Performance trends / Overseas sales

(Unit: Billion yen)

Overseas sales have increased 112.4 billion yen, up 175%, over the last 10 years with average annual growth of 10.6%.

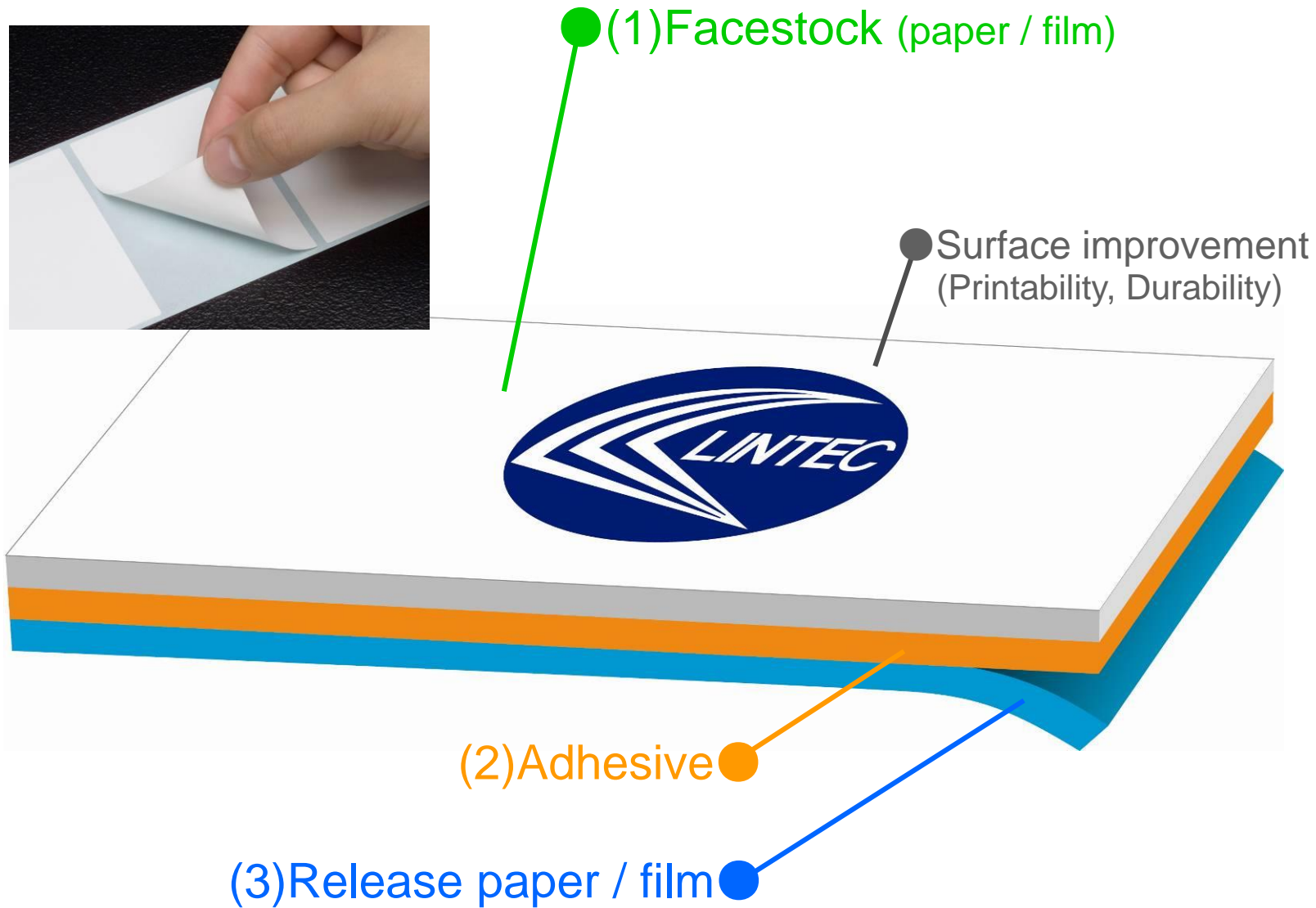


33.7%

Ratio of overseas sales to net sales

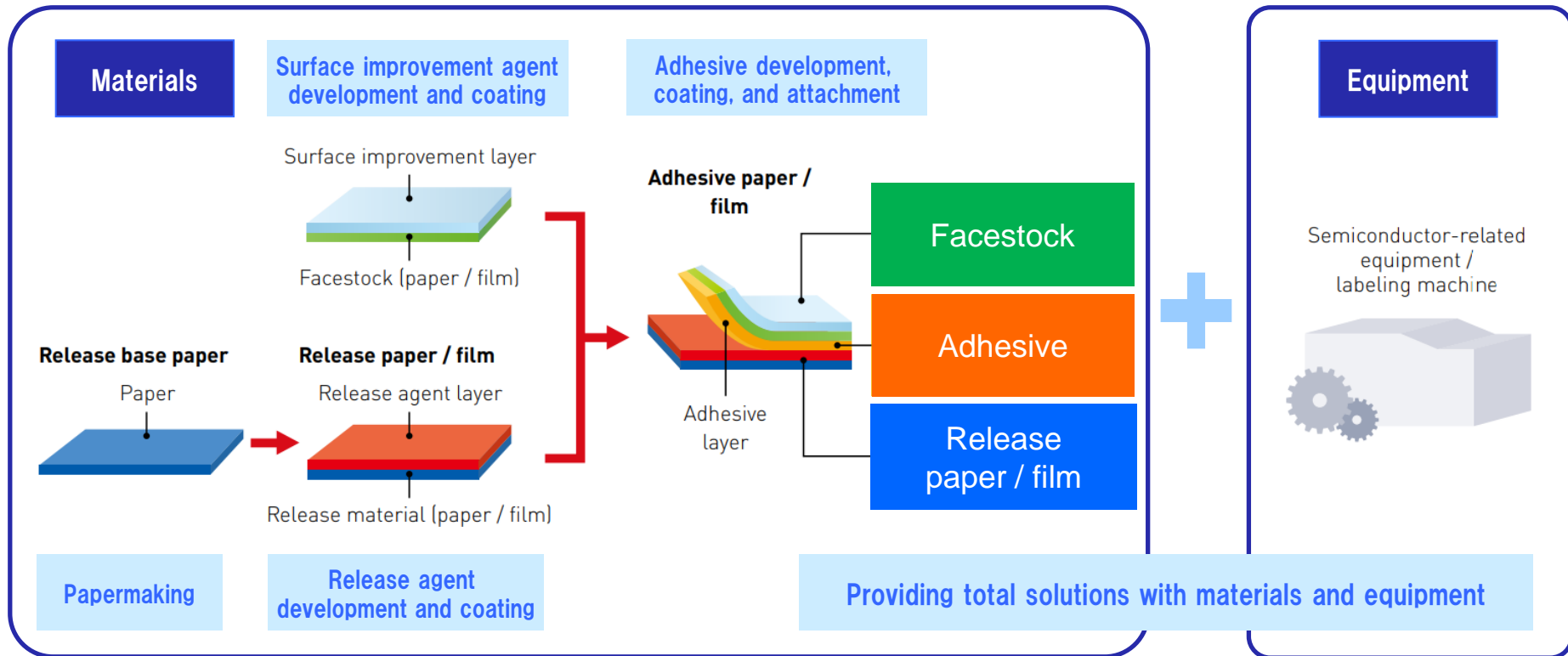
62.1%

Basic composition of adhesive products



Meeting needs with in-house technologies

Integrated production of adhesive products



- We have built an integrated production system for adhesive products by producing release base paper, developing and coating release agent and adhesives, and processing facestock.
- By developing and manufacturing related equipment that fully draws out the special characteristics of our adhesive products, we are providing total solutions with materials and equipment.

Four core technologies

1

Adhesive applications

Through the development of adhesives and substrates and the combination of related technologies, we are expanding the range of fields in which the basic functions of adhesive products, primarily adhesion and release, are utilized.

2

Surface improvement

Through the chemical and physical processing of the surfaces of paper and film, we are enhancing their characteristics and adding new functionality.

3

System development

Through the systemization of machinery and equipment and building high-level systems that draw on the distinctive characteristics of materials, we are providing advanced solutions.

4

Specialty paper and Release materials production

We use original papermaking technologies and coating, impregnation, and laminating technologies to develop special function paper and high-value-added materials that transcend traditional concepts of paper.

Four core technologies and operational segments

Core technologies

1

Adhesive applications

2

Surface improvement

3

System development

4

Specialty paper and
Release materials production

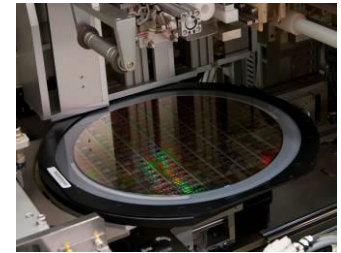
Printing and Industrial Materials Products

- Printing & Variable Information Products Operations
- Industrial & Material Operations



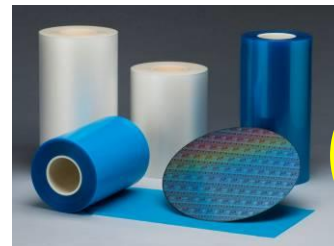
Electronic and Optical Products

- Advanced Materials Operations
- Optical Products Operations



Paper and Converted Products

- Fine & Specialty Paper Products Operations
- Converted Products Operations



Adhesive
products
+
Equipment



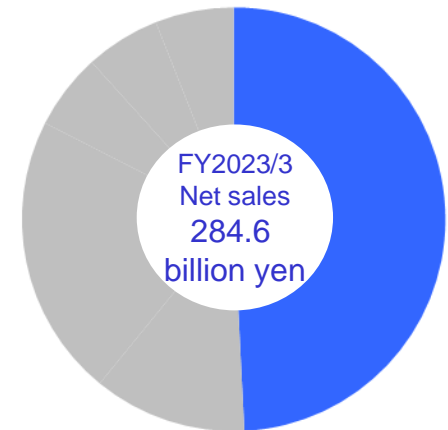
● Adhesive papers and films for labels

- Main types : Permanent, Removable, Restickable
- Properties : Printability, Durability, Heat resistance, Water resistance, Cold resistance, Curved-surface adhesion, Dimensional stability, Design and others.

【Commercial flow】

LINTEC ⇒ Seal & Label printing company ⇒ End users

Sales in this operation
140.0 billion yen
49.2%



Usage of adhesive papers and films for labels / Required properties



- For food- and drink-related products
 - Water resistance
 - Curved-surface adhesion
 - Cold resistance etc.



- For commodity items
 - Water resistance
 - Curved-surface adhesion
 - Design etc.



- For consumer electronics-related products
 - Durability
 - Heat resistance
 - Outgassing resistance etc.



- For automobile-related products
 - Oil- and water-resistance
 - Durability
 - Heat resistance etc.



- For medical and pharmaceutical items
 - Printability
 - Chemical resistance
 - Tamper-evident etc.



- For distribution and mail-order products
 - Printability
 - Adequacy for affixing seals
 - Cold resistance etc.



MACTAC AMERICAS, LLC

- In December 2016, Lintec Group acquired Mactac Americas, the third largest manufacturer of adhesive products for seals and labels in North America, at an acquisition price of approx. 34.0 billion yen in order to make full-scale entry into the North American Market.
- Goodwill : Approx. 30 billion yen (depreciation over 10 years)
- In Apr. 2021, Mactac Americas acquired **Duramark Products, Inc.** in the same industry at an acquisition price of approx. 6.5 billion yen in order to increase the Mactac Group's production capacity.
- In Feb. 2022, Mactac Americas established **Spinnaker Pressure Sensitive Products LLC** through a business transfer from a manufacturer in the same industry for approx. 4.5 billion yen, for the purpose of expanding its business fields.

Establishment : 1959

Registered Office : Ohio, USA

Number of Employees : 1,038 (as of Dec. 31, 2022)

Business Description :

Manufacture and sales of label materials for printing, VIP label materials, graphic sheets, industrial and medical tapes, etc.

Acquisition Price : Approx. USD 300 million

● DURAMARK PRODUCTS, INC. (South Carolina, USA)

- The company has cutting-edge facilities for production compatible with various types of adhesive formulations and high-speed coating and contributes to an increase in the Mactac Group's production capacity (merged in Dec. 2021).
- Sales volume at the time of acquisition: 8.0 billion yen
- Negative goodwill: 0.3 billion yen (one-time amortization)

● SPINNAKER PRESSURE SENSITIVE PRODUCTS LLC (Ohio, USA)

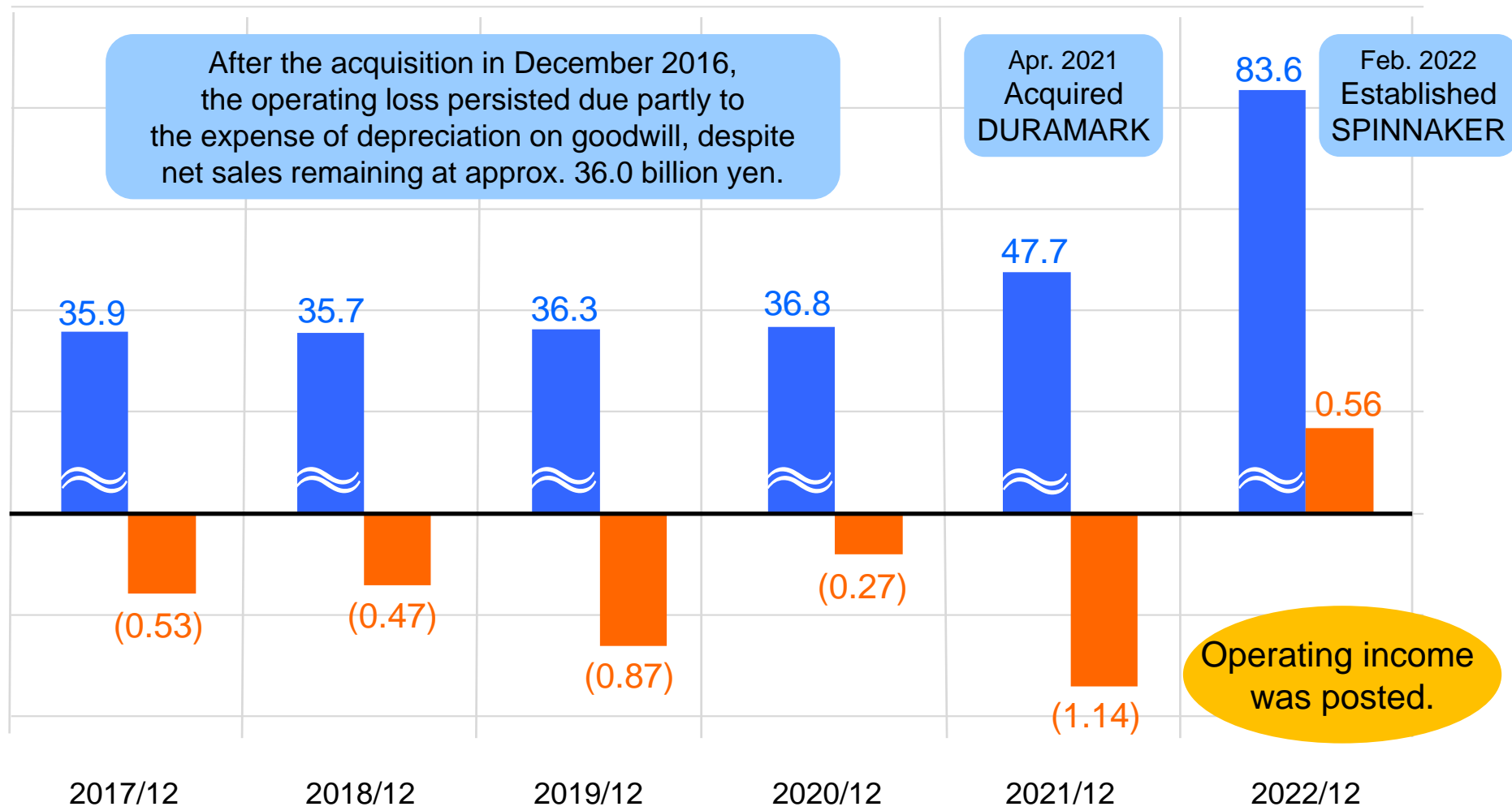
- The company is preeminent in areas that are different from those of Mactac Americas, such as multi-type, small-quantity production, and contributes to the Mactac Group's business field expansion.
- Sales volume at the time of acquisition: approx. 13.0 billion yen
- Goodwill: approx. 1.0 billion yen (depreciation over 10 years)

Performance trend of MACTAC Group

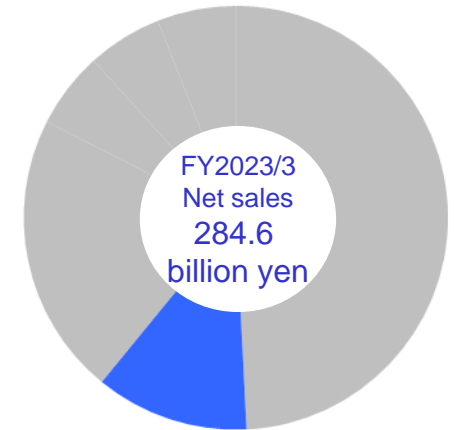
Unit: Billion yen

Net sales

Operating income



- Window films(for buildings / automotive)
- Graphic films
- Automobile-use adhesive products
- Industrial-use adhesive tapes
- Labeling machines, Barcode printers etc.



Sales in this operation
33.3 billion yen
11.7%



Main products and features of the Industrial & Material Operations

● Window films for buildings



- Glass Shatterproof
- Solar Control
- UV protection etc.

● Paint replacement films for door sashes



- Weatherability
- Construction suitability etc.

● Automotive films



- Glass Shatterproof
- Solar Control
- UV protection etc.

● Protective films for aluminum wheels



- Weatherability
- Re-sealability etc.

● Graphic films



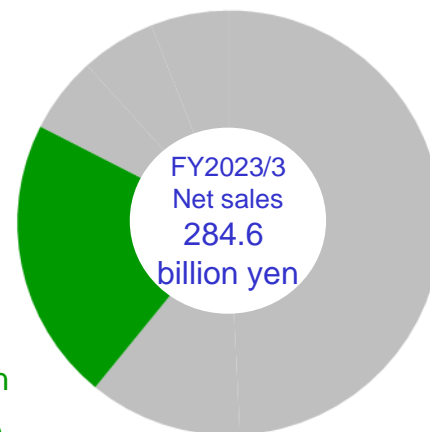
- Weatherability
- Construction suitability
- Rich variety etc.

● Labeling machines

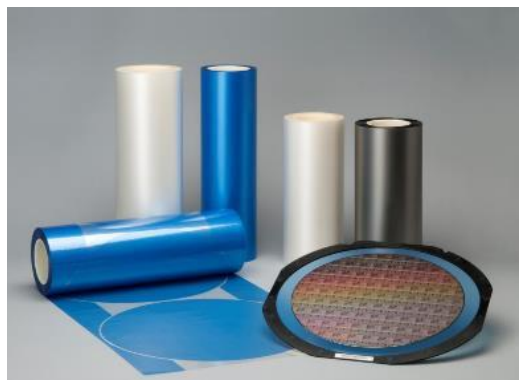


- Faster and more efficient
- Workability
- Automation etc.

- Semiconductor-related adhesive tapes
 - Back grinding tapes
 - Dicing tapes
 - Backside coating tapes
 - Dicing die bonding tapes
- Semiconductor-related equipment
 - Wafer mounter
 - Tape laminator & remover
 - UV irradiation system
- Multilayer ceramic capacitor-related tapes, etc.



Sales in this operation
61.5 billion yen
21.6%



■ Manufacturing process for semiconductor

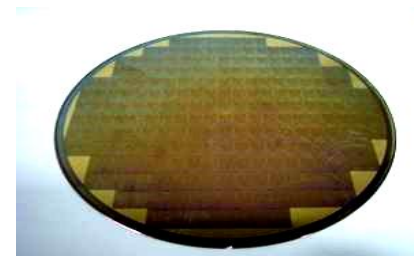
【Fabrication】



Single crystal silicon ingot



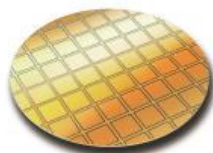
Wafer



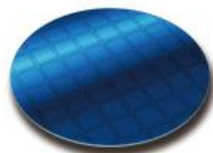
Wafer following circuit formation

【Back-end process】

*Uses of our tapes and equipment



Wafer following circuit formation



Lamination of surface protective tape*



Back grinding (wafer thinning)



Lamination of dicing tape*



Removal of surface protective tape*



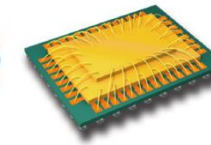
Dicing (wafer cutting)



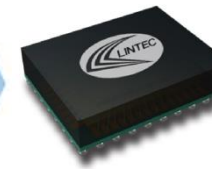
UV irradiation of tape*



Picking up



Mounting / Stacking



Molding

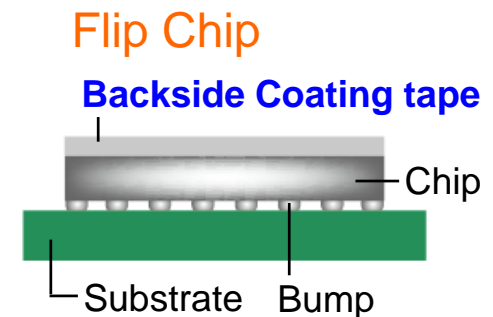
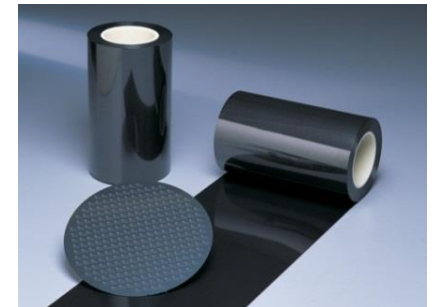
● Key tape products related to semiconductors

● Backside coating tape for Flip Chip

- This tape protects and reinforces the die backside in applications such as Flip Chip, in which some bumps(electrodes) is formed on the circuit surface and mounted onto a substrate.

【Main features】

- It blocks light to minimize effects on the circuit surface
- Unlike a coating of liquid mold material, this product is available as a tape, ensuring outstanding uniformity in thickness, and allowing the simplification of conventional processes
- Applicable at a relatively low temperature, it inflicts less thermal damage to circuits. Combined with our tape laminator, it helps construct a production line with greater reliability.
- We have broad lineups of the tapes including Infrared Transmission Type and Dicing Tape Integrated Type



● Key tape products related to semiconductors

● Wafer surface protective tape for use in SDBG

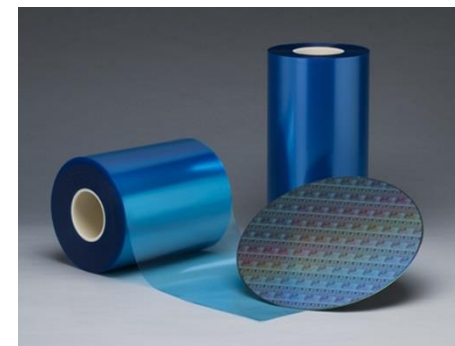
- This tape is designed to protect the circuit surface when grinding the back side of the wafer in the SDBG* process.

* SDBG stands for Stealth Dicing Before Grinding. It is a processing technology of grinding the back side of the wafer after making cracks in the wafer with a laser. It allows more chips to be taken from a single wafer and produces stronger chips than the conventional process using blades.

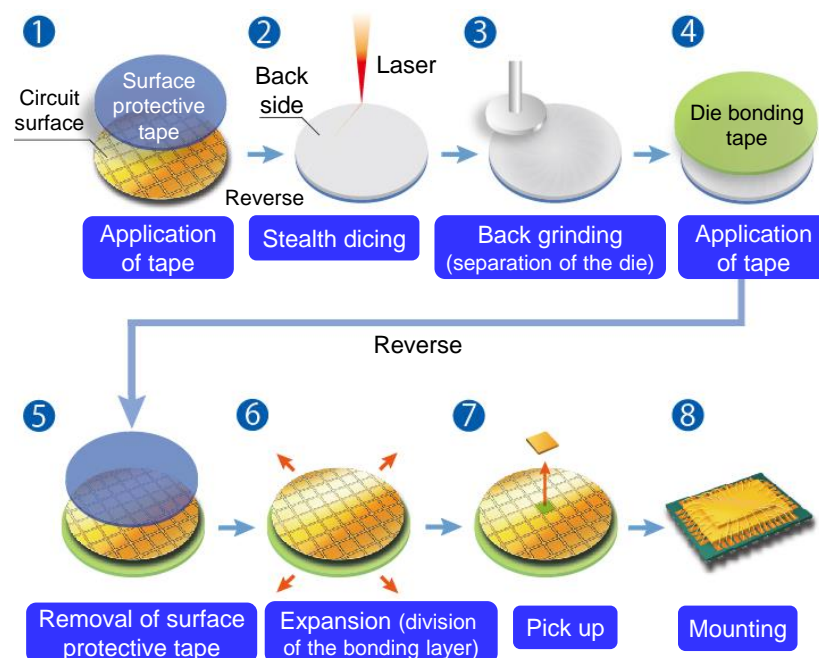
Note: Stealth Dicing is a laser dicing technology developed by Hamamatsu Photonics K.K.

【Main features】

- A high adhesive strength prevents chip scattering and grinding fluid intrusion.
- It reduces chip damage at the time of back grinding.
- It is applicable to the manufacturing of chips with a thickness of 30μm or less.

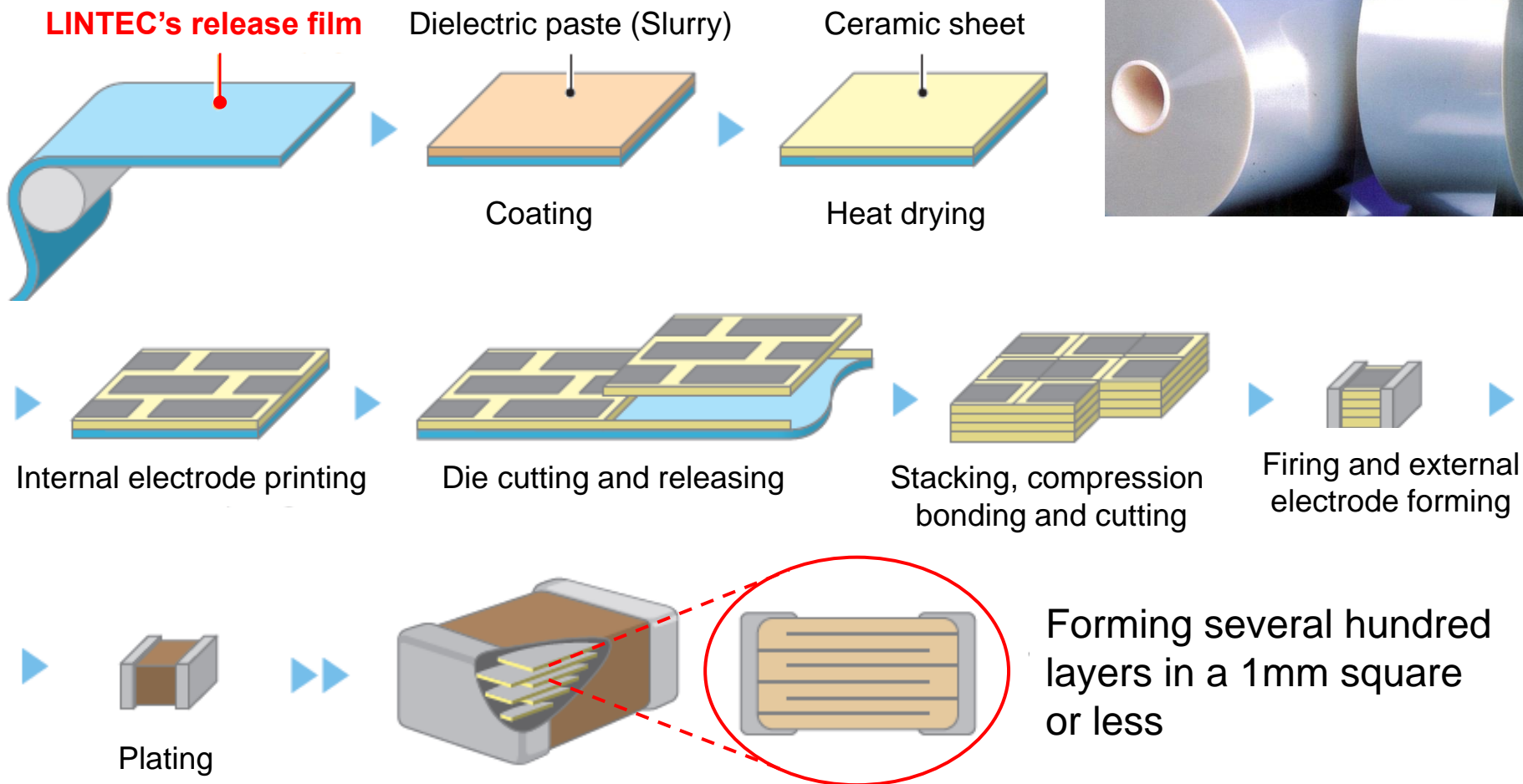


■ Semiconductor production process using SDBG



● Multilayer ceramic capacitor (MLCC) –related tapes

■ Manufacturing process for MLCC



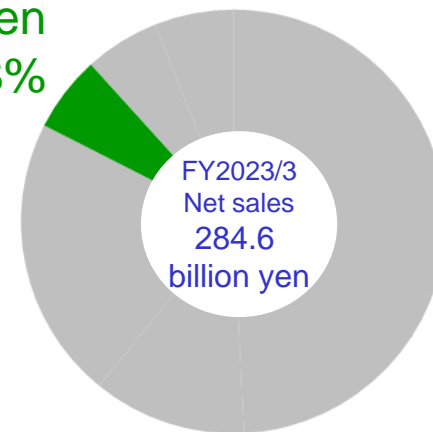
- Optical display-related adhesive products

- Polarizing film

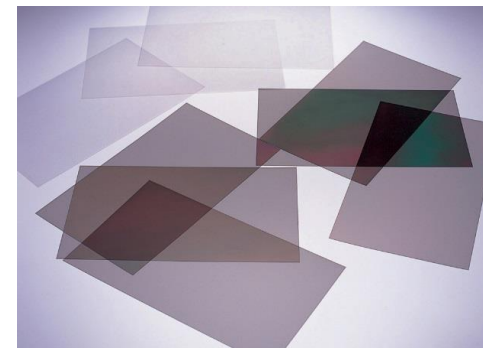
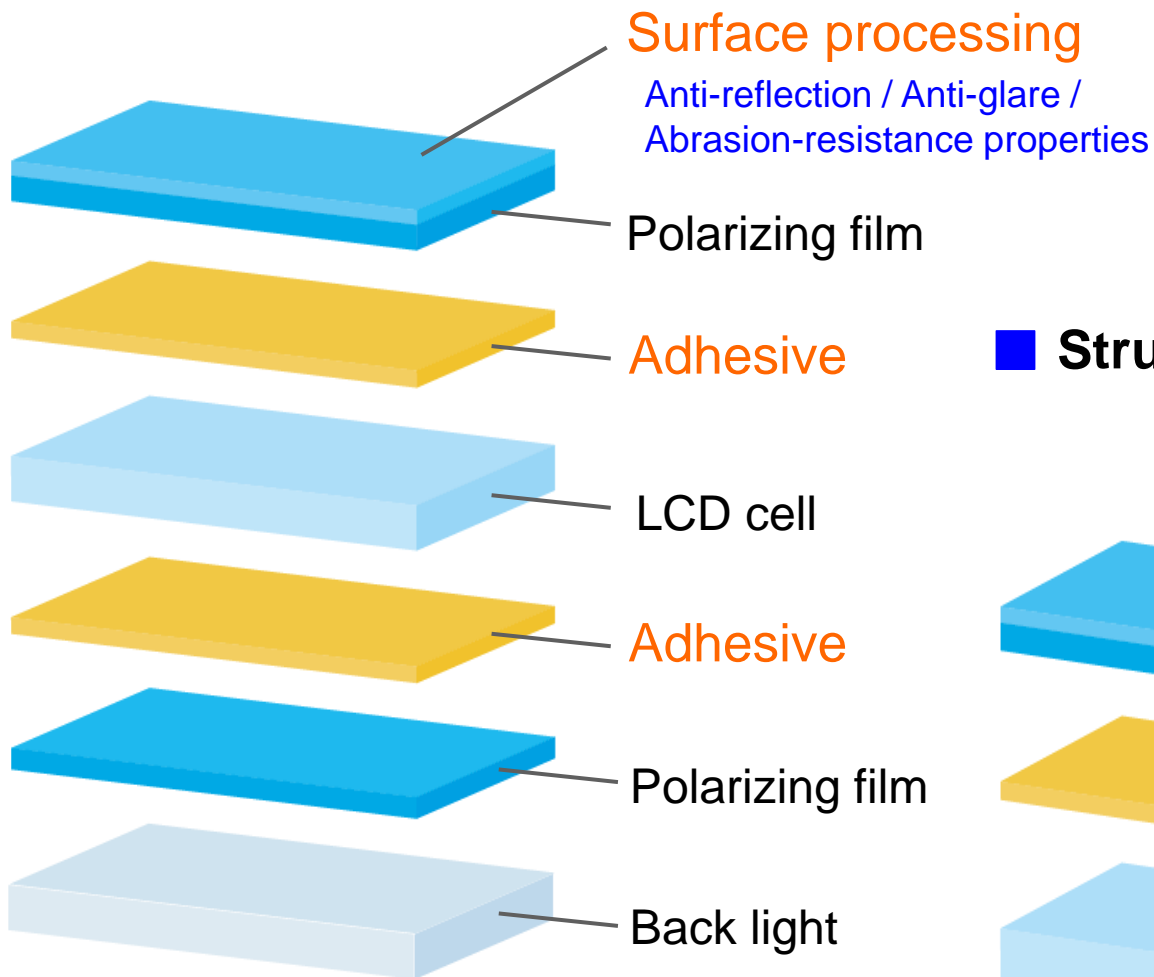
- Adhesive processing / Non-carrier type products

- Touch screen-related products, etc.

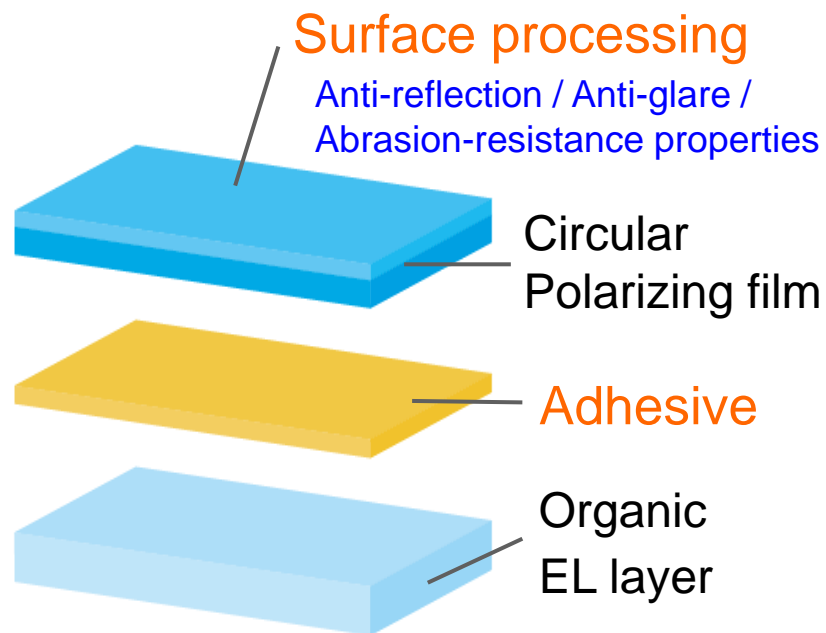
Sales in this operation
16.6 billion yen
5.8%



■ Structure of LCD



■ Structure of OLED



● Key products related touch screen

● Onboard optical clear adhesive sheets

- Highly functional optically double-sided adhesive sheets that are used to bond onboard touch screen

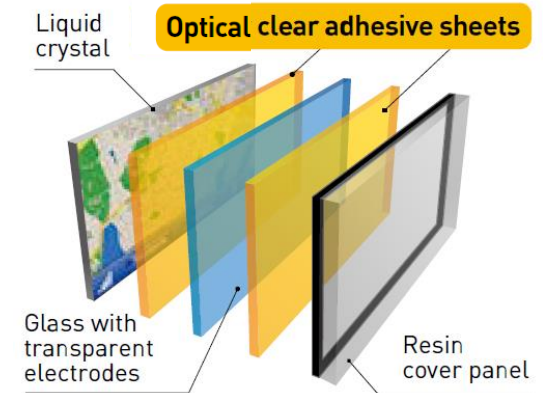
【Main features】

- Meet the rigorous durability standards required for use in automotive applications
- Prevent outgassing from the plastic resin

● Light diffusion films

- Optically functional film that provides efficient, optimal diffusion of incident light in the necessary direction
- Make reflective displays, which do not use backlighting brighter than before

■ Diagram of an onboard touch screen



■ Example used of light diffusion films



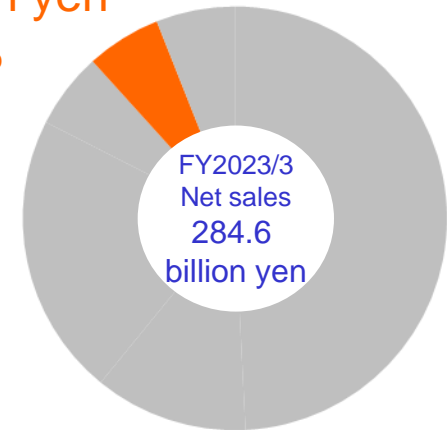
Smart watches



GPS navigation system for bicycles

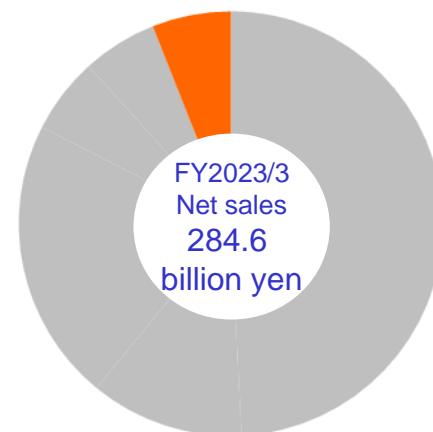
- Color papers for envelopes
- Colored construction papers
- Special function papers
(Oil-and water-resistant papers, Dust-free papers, etc.)
- High-grade printing papers
- Construction material paper, etc.

Sales in this operation
16.1 billion yen
5.7%



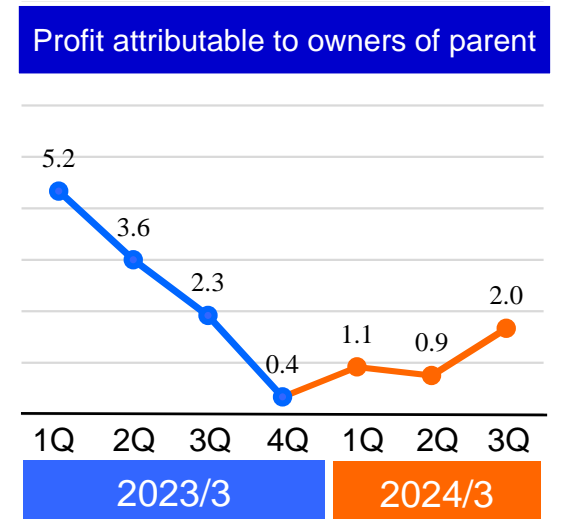
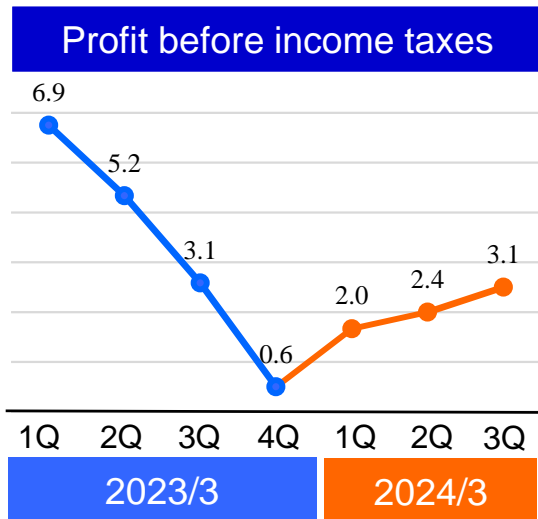
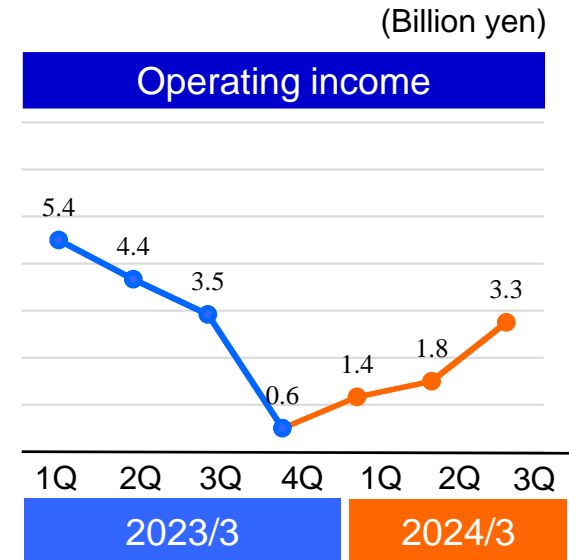
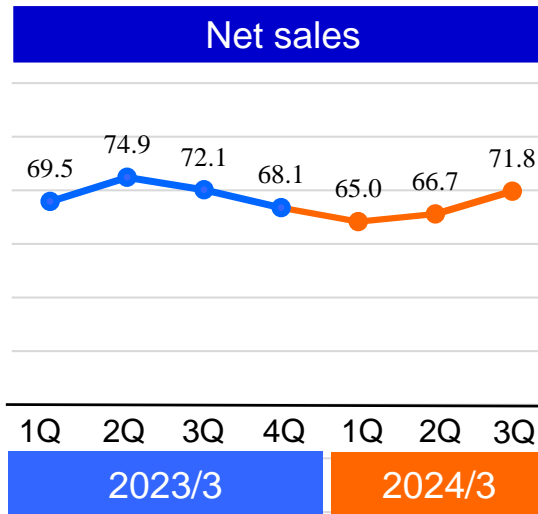
- Release papers for adhesive products
- Release papers for electronic materials
- Release films for optical-related products
- Casting papers for synthetic leather
- Casting papers for carbon fiber composite materials, etc.

Sales in this operation
17.1 billion yen
6.0%

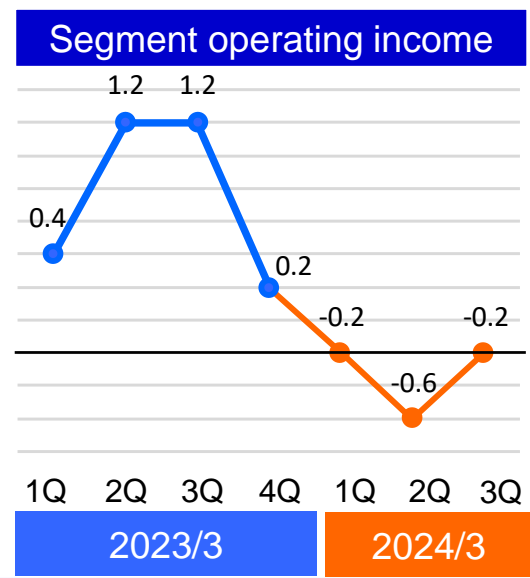
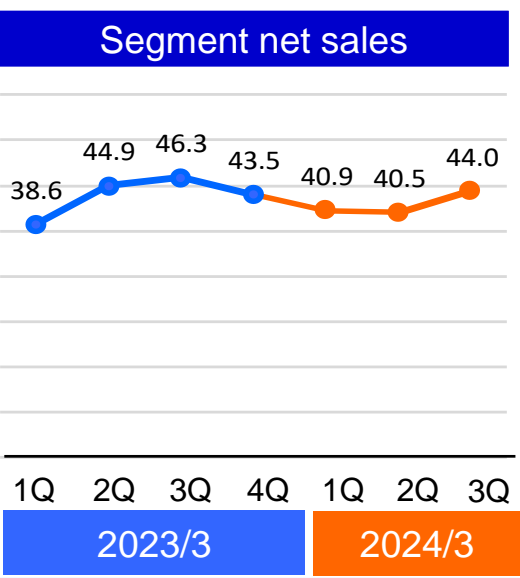
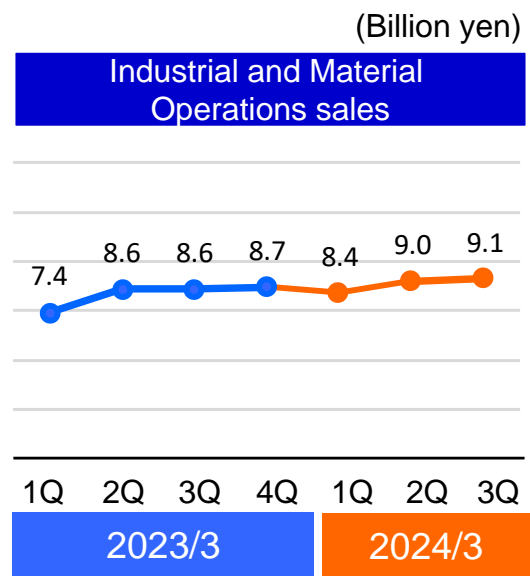
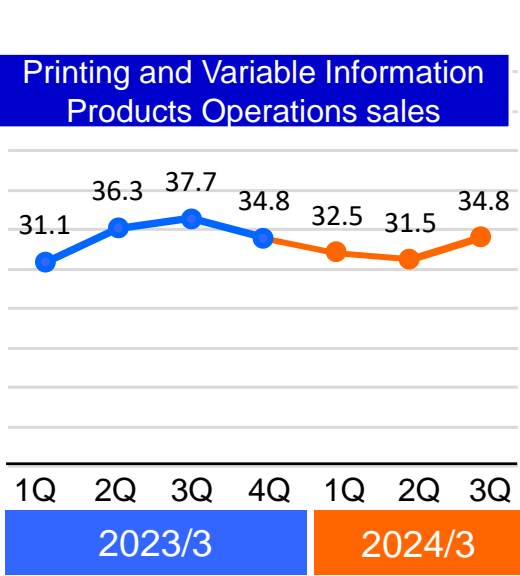


Consolidated financial results for second quarter FY2024/3

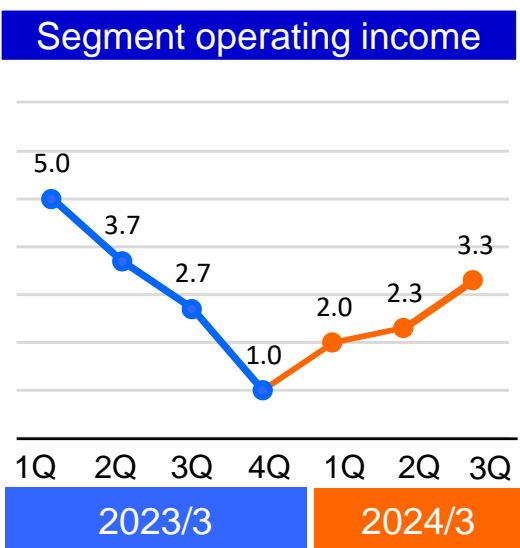
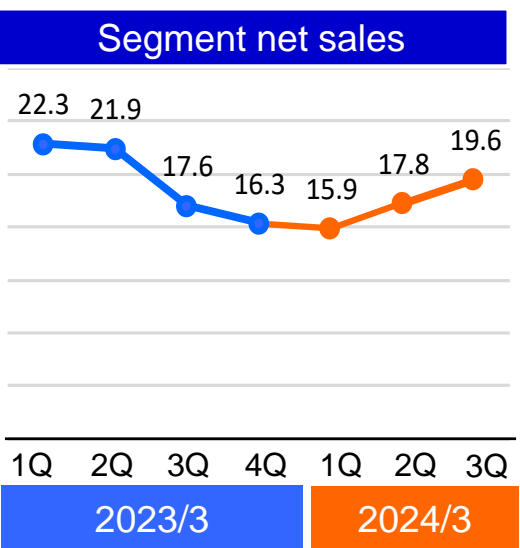
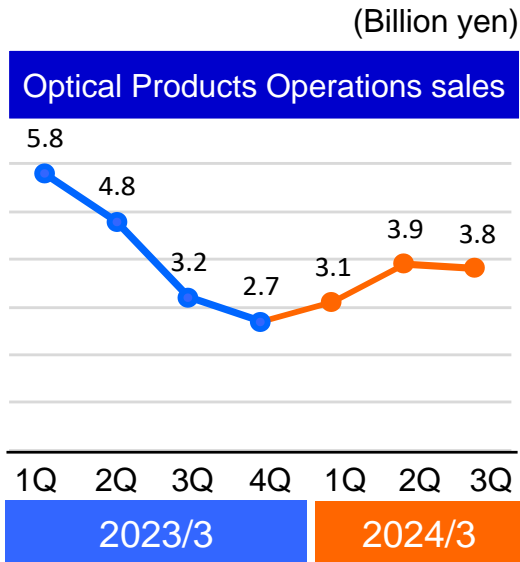
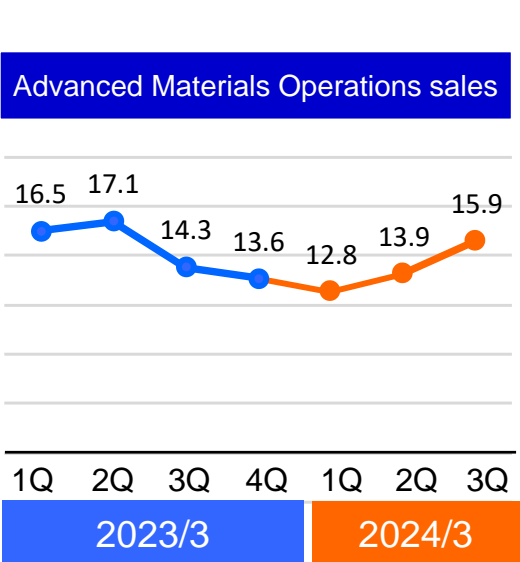
	(Billion yen)		
	2024/3 3Q results	2023/3 3Q results	Increase (decrease)
Net sales	203.5	216.6	(13.0) (6.0%)
Operating income	6.5	13.2	(6.7) (50.8%)
Profit before income taxes	7.4	15.2	(7.8) (51.2%)
Profit attributable to owners of parent	4.0	11.1	(7.1) (63.9%)



	(Billion yen)		
Printing and Industrial Materials Products	2024/3 3Q results	2023/3 3Q results	Increase (decrease)
Printing and Variable Information Products Operations	98.9	105.2	(6.3) (6.0%)
Industrial and Material Operations	26.5	24.6	1.9 7.6%
Segment net sales	125.4	129.8	(4.4) (3.4%)
Segment operating income	(1.0)	2.7	(3.7) - %



	(Billion yen)		
Electronic and Optical Products	2024/3 3Q results	2023/3 3Q results	Increase (decrease)
Advanced Materials Operations	42.6	47.9	(5.3) (11.1%)
Optical Products Operations	10.7	13.9	(3.1) (22.7%)
Segment net sales	53.3	61.8	(8.5) (13.7%)
Segment operating income	7.6	11.5	(3.9) (33.6%)



Net sales / Operating income by operational segment

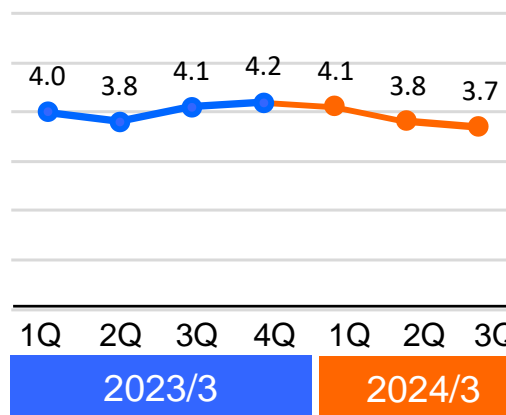
Paper and Converted Products

(Billion yen)

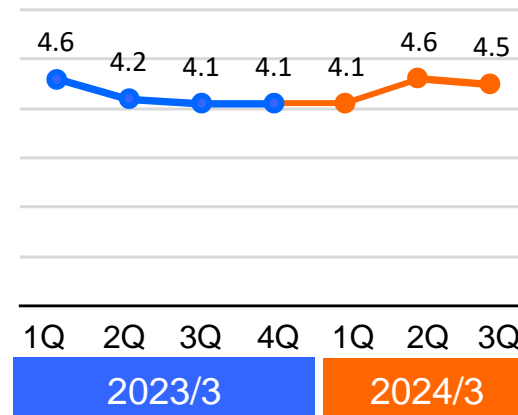
Paper and Converted Products	2024/3 3Q results	2023/3 3Q results	Increase (decrease)
Fine and Specialty Paper Products Operations	11.6	12.0	(0.4) (3.4%)
Converted Products Operations	13.3	13.0	0.2 1.7%
Segment net sales	24.8	25.0	(0.2) (0.7%)
Segment operating income	(0.2)	(1.0)	0.8 -%

(Billion yen)

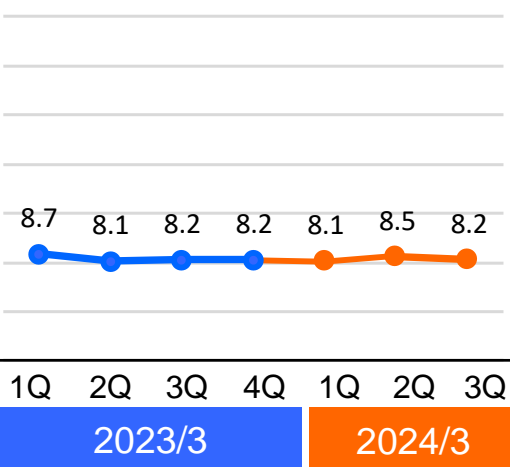
Fine and Specialty Paper Products Operations sales



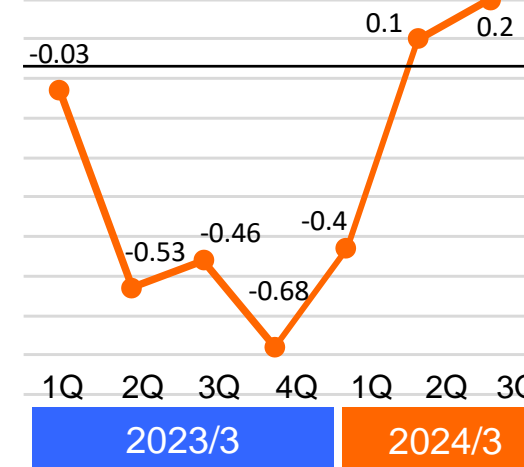
Converted Products Operations sales



Segment net sales



Segment operating income



Forecasts of consolidated financial results for FY2024/3

(Billion yen)

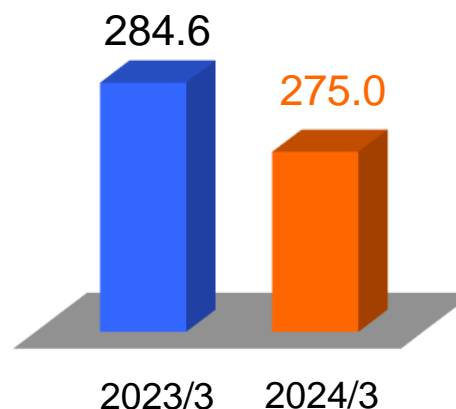
	2024/3 full year forecasts	2023/3 full year results	Increase (decrease)
Net sales	275.0	284.6	(9.6) (3.4%)
Operating income	9.0	13.8	(4.8) (34.8%)
Profit before income taxes	10.0	15.9	(5.6) (35.9%)
Profit attributable to owners of parent	5.5	11.5	(6.0) (52.2%)

Unit: Billion yen

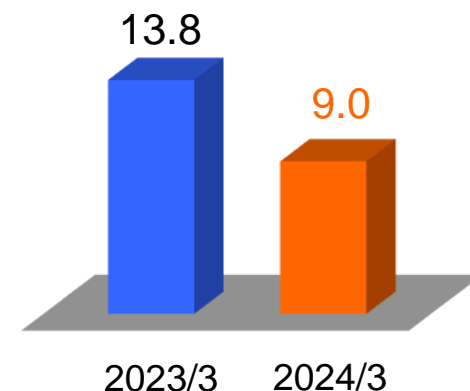
Result

Forecast

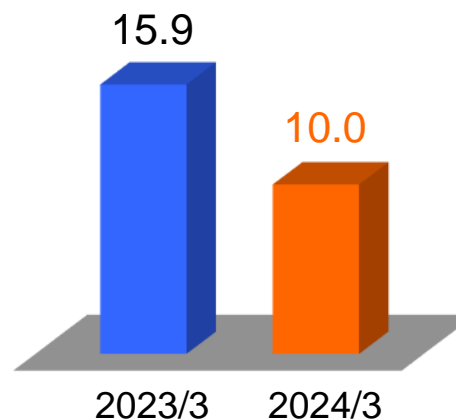
Net sales



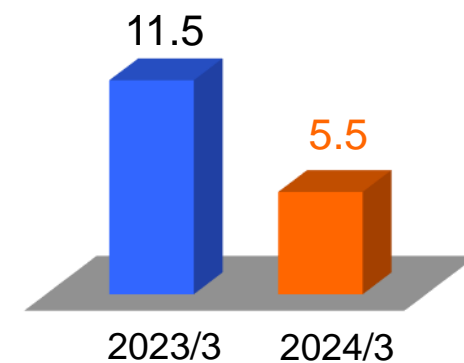
Operating income



Profit before income taxes



Profit attributable to owners of parent

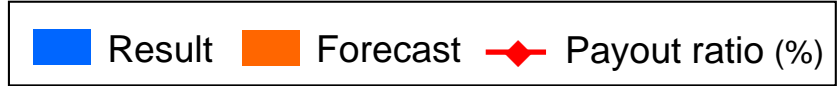


Forecasts of net sales and operating income for FY2024/3 by operational segment

	(Billion yen)			(Billion yen)			(Billion yen)				
	2024/3 forecasts	2023/3 results	Increase (decrease)		2024/3 forecasts	2023/3 results	Increase (decrease)		2024/3 forecasts	2023/3 results	Increase (decrease)
Printing and Industrial Materials Products				Electronic and Optical Products				Paper and Converted Products			
Printing and Variable Information Products Operations	135.2	140.0	(4.8) (3.4%)	Advanced Materials Operations	58.0	61.5	(3.5) (5.7%)	Fine and Specialty Paper Products Operations	15.6	16.1	(0.5) (3.2%)
Industrial and Material Operations	35.3	33.3	2.0 6.0%	Optical Products Operations	13.4	16.6	(3.2) (19.3%)	Converted Products Operations	17.5	17.1	0.4 2.5%
Segment net sales	170.5	173.3	(2.8) (1.6%)	Segment net sales	71.4	78.1	(6.6) (8.5%)	Segment net sales	33.1	33.2	(0.1) (0.3%)
Segment operating income	(0.8)	3.0	(3.8) -%	Segment operating income	10.5	12.5	(2.0) (16.1%)	Segment operating income	0.7	(1.7)	1.0 -%

Dividend

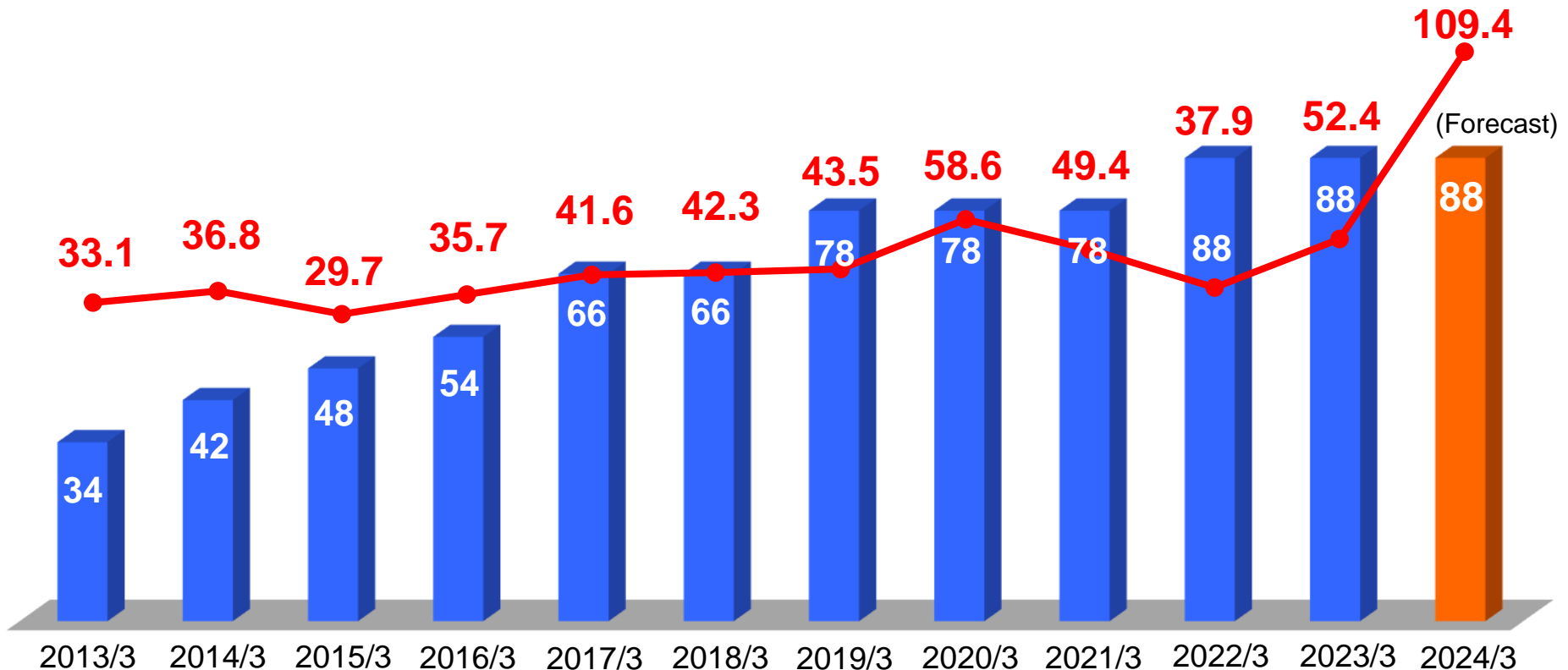
● Trend in dividends per share (yen)



● Changed dividend policy from the fiscal year ending March 31, 2024

In principle, we will not reduce the dividend for the four years until the fiscal year ending March 31, 2027, which is the final year of the next medium-term management plan LSV 2030 - Stage 2.

We will pay dividends to achieving a payout ratio of at least 40% or a DOE of approximately 3%.





Name **LINTEC SUSTAINABILITY VISION 2030** (Abbreviation : LSV 2030)

Term April 2021 to March 2030

Basic Policy

Contribute to realizing a sustainable world by strengthening the corporate structure through innovation and creating new products and businesses for sustainable growth

Key Initiatives

1. Solve social issues
2. Foster innovation to build a robust corporate structure
3. Create new products and businesses to deliver sustainable growth

Financial Indicators (FY2030/3)

Operating Profit Margin

12% or more

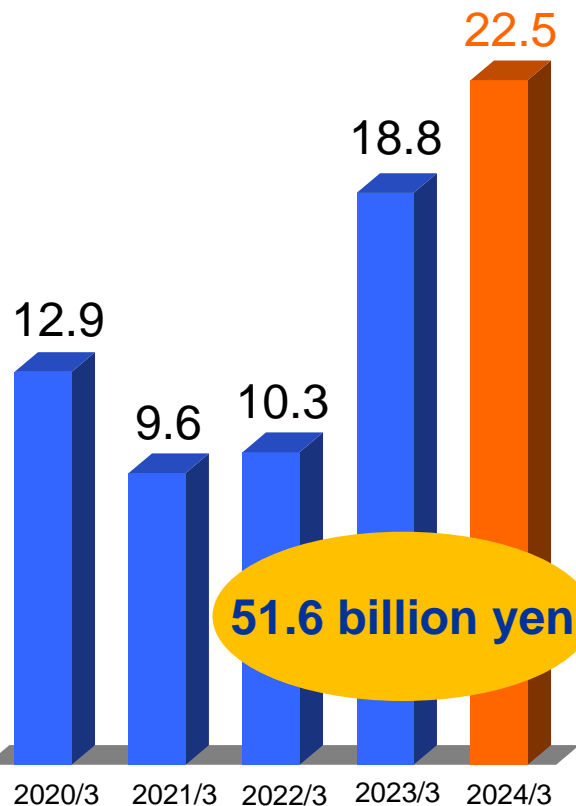
ROE(Return on Equity)

10% or more

Capital expenditure, Depreciation, Amortization of goodwill, R&D expenses

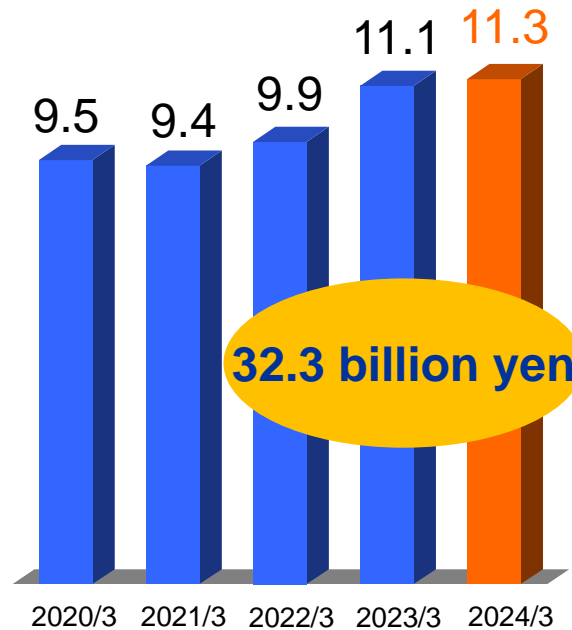
Unit : Billion yen ■ Result ■ Forecast

Capital expenditure



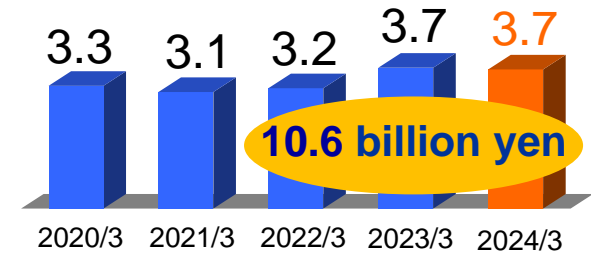
LSV 2030-Stage 1

Depreciation



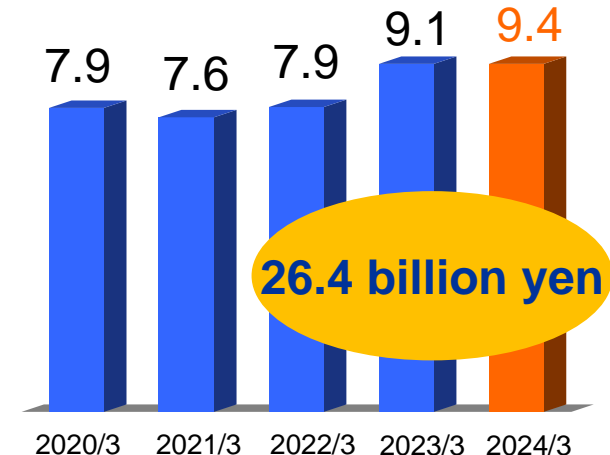
LSV 2030-Stage 1

Amortization of goodwill



LSV 2030-Stage 1

R&D expenses



LSV 2030-Stage 1

This material includes forward-looking statements, such as forecasts of business results, based on information currently held and assumptions that have been judged as reasonable by the Company.

The Company cannot guarantee the accuracy of these statements or definitively assure the realization of future numerical targets and policies.

Actual business results, etc., may vary due to various factors and circumstances.